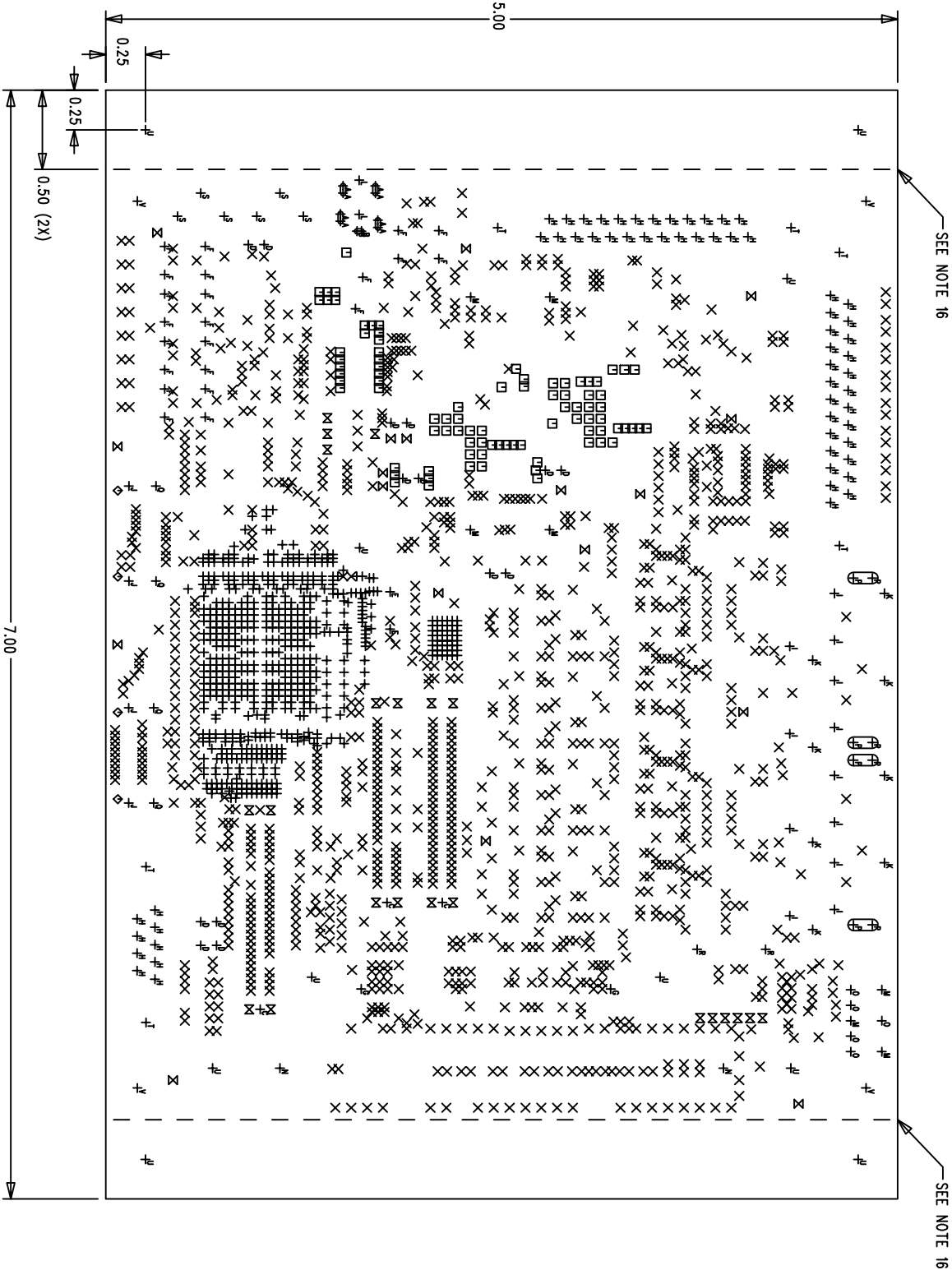
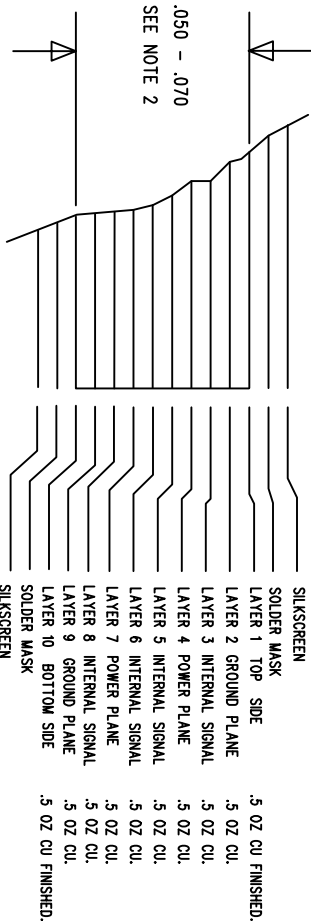


REVISIONS			
REV	DESCRIPTION OF CHANGE	DRT/1R DATE	APPROVED
0.1	NEW RELEASE	C.C.D. 12/16/08	
0.2	REFER TO ECO2009-016	C.C.D. 03/19/09	

SIZE	QTY	SYM	PLATED	TOL
0.008	640	+	YES	+/-0.003
0.012	1317	×	YES	+/-0.003
0.02	88	□	YES	+/-0.003
0.025	4	◇	YES	+/-0.003
0.028	18	⊗	YES	+/-0.003
0.032	22	⊗	YES	+/-0.003
0.032 x 0.078	4	+	YES	+/-0.003
0.032 x 0.06	1	+	YES	+/-0.003
0.033	3	+	NO	+/-0.003
0.038	14	+	YES	+/-0.003
0.039	2	+	NO	+/-0.003
0.043	22	+	YES	+/-0.003
0.046	2	+	NO	+/-0.003
0.047	59	+	YES	+/-0.003
0.051	12	+	YES	+/-0.003
0.057	4	+	NO	+/-0.003
0.059	8	+	YES	+/-0.003
0.063	2	+	NO	+/-0.003
0.068	7	+	NO	+/-0.003
0.07	2	+	NO	+/-0.003
0.071	5	+	YES	+/-0.003
0.071 x 0.19	4	+	NO	+/-0.003
0.075	4	+	YES	+/-0.003
0.079	2	+	YES	+/-0.003
0.085	6	+	YES	+/-0.003
0.125	6	+	YES	+/-0.005
0.125	10	+	NO	+/-0.005
0.156	4	+	NO	+/-0.005



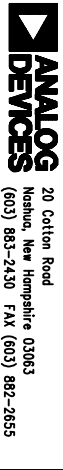
10 LAYER CONSTRUCTION DETAIL  
SCALE : NONE



SCORING DETAIL  
2 PLACES

- UNLESS OTHERWISE SPECIFIED
- BOARD TO BE FABRICATED PER IPC-6012B, CLASS 2.
- MATERIAL: FR-370HR OR EQUIVALENT. OUTER LAYERS 1/2 OZ/SOFT CU INNER LAYERS 1/2 OZ/SOFT CU FINISHED .062 (.050 MIN .070 MAX SEE DETAIL). VENDOR MAY ADJUST THICKNESS TO FULFILL NOTE 9.
- PLATING: ADDITIONAL CU PLATING 1 OZ/SOFT. ALL HOLES PLATED THROUGH, EXCEPT AS NOTED IN HOLE LEGEND. MINIMUM PTH BARREL THICKNESS = 0.0009". MINIMUM AVERAGE PER IPC-6012B WITH AMENDMENT 1, CLASS 2 REQUIREMENTS. WITH NO SINGLE MEASUREMENT LESS THAN 0.00071 IN THE PLATED HOLES.
- FINISH: SURFACES TO BE COATED BY ENIG OF 3 TO 5 MICRONS OVER A MINIMUM OF 150-200 MICRONS OF LOW STRESS NICKEL.
- SOLDERMASK: SOLDER MASK TO BE TRANSPARENT GREEN LPI BOTH SIDES PER GERBER FILES.
- SILKSCREEN: WHITE EPOXY INK, APPLY TO BOTH SIDES PER GERBER FILES. MINIMUM FEATURE SIZE = 0.005 MINIMUM AIR GAP = 0.004
- ALL DIMENSIONS ARE IN INCHES.
- CONTROLLED IMPEDANCE: BOARD TO BE BUILT TO YIELD CONTROLLED IMPEDANCE OF 60 OHMS +/-10% (SINGLE ENDED) ON ALL .005" LINE WIDTHS. ALL .0049" LINE WIDTHS TO BE 100 OHMS DIFFERENTIAL +/-10%.
- NON-FUNCTIONAL COPPER THEIVING IS ALLOWED ON OPEN AREAS.
- VIAS SHOULD BE COVERED ACCORDING TO ONE OF THE FOLLOWING METHODS. METHOD 1 IS PREFERRED. METHOD 1: VIAS MUST BE FILLED WITH SOLDERMASK MATERIAL AFTER ELECTROLESS NICKEL/IMMERSION GOLD AND BEFORE PRIMARY LPI MASK. AFTER THE FILL IS CURED, THE PRIMARY MASK IS THEN APPLIED WITH NO VIA APERATURES BOTH SIDES.
- METHOD 2: AFTER APPLICATION OF FULL BODY ELECTROLESS NICKEL/IMMERSION GOLD, APPLY PRIMARY MASK WITH REDUCED VIA APERTURES THAT ARE 6 MILS LARGER THAN DRILLED HOLE DIAMETER BOTH SIDES. THEN APPLY SOLDER MASK PLUG ON COMPONENT SIDE.
- VIA HOLES (.008 & .012) REQUIRE TANGENCY ONLY, INSTEAD OF ANNULAR RING.
- TEARDROP PADS ARE ACCEPTABLE WHERE NEEDED.
- REMOVAL OF NON-FUNCTIONAL PADS ON LAYERS 3, 5, 6, AND 8 IS ACCEPTABLE.
- USE IPC-D-356A NETLIST AS SUPPLIED FOR CHECKING.
- V SCORE 1 LINE ON BOTH SIDES OF THE BOARD. SEE DETAIL.
- BUILD AS 1-UP PCB.
- THE FOLLOWING NETS ARE INTENTIONALLY SHORTED AND RESULT IN IPC NETLIST ERRORS: AT W1 : GND & PGND (LAYER 1) AT W2 : GND & PGND2 (LAYER 1)
- UNUSED PINS ARE TIED TO A NET CALLED "NOT CONNECTED" AND BROUGHT OUT TO VIAS. THIS RESULTS IN IPC NETLIST ERRORS. THESE ARE INTENTIONAL.

UNLESS OTHERWISE SPECIFIED		CONTRACT NO.	
DIMENSIONS ARE IN INCHES		APPROVALS	
TOLERANCES ARE : .XX +/- .010 .XXX +/- .005		DATE	
MATERIAL		C.C.D.	
SEE NOTES		03/19/09	
CHECKED			
ENGINEERING			
QUALITY			
DO NOT SCALE THIS DRAWING		SCALE	
		1 : 1	
		SHEET	
		1 OF 1	



FABRICATION DRAWING  
ADSP-21469 EZ-BOARD

SIZE  
DWG. NO. A0221-2008  
REV. 0.2